

**IN THE SPECIFICATION**

On page 2 prior to the paragraph starting on line 2, please insert the following:

A1 This application is a divisional patent application of U.S. Patent Application No. 09/527,284, filed March 17, 2000, now pending, which is a divisional patent application of U.S. Patent Application No. 08/986,275, filed December 5, 1997, now U.S. Patent No. 6,064,117.

On page 4, please replace the paragraph starting on line 14 with the following paragraph:

A2 As a result of this construction, the corner sections 19 of prior PBGA assemblies 10 are susceptible to mechanical damage. The flexible corner sections 19 are easily damaged, for example, during processing associated with the assembly, test, and installation of the PBGA assemblies 10, and during normal handling.

On page 9, please replace the paragraph starting on line 12 with the following paragraph:

A3 Although the solder balls 120 can be located across the entire lower surface of the substrate 114, in accordance with one embodiment of the present invention, the solder balls 120 are spaced from the areas directly beneath the edges of the die 22. Shear stress tends to be the greatest during temperature cycling in the area directly beneath the edges of the die 22, and thus, after a relatively few number of thermal cycles, the solder balls 120 tend to fail. However, beneath the die 22 but spaced from the edges thereof, the solder balls 120 can also serve as a heat transfer path into the printed circuit board. Thus, in one embodiment depicted in Figure 5, about five rows 200 of solder balls 120 are disposed generally around the edges of the substrate 114. Additionally, a plurality of central solder balls 202 are spaced from the peripheral solder balls